

MOSFET – N-Channel, Shielded Gate, POWER trench®

80 V, 6.5 mΩ, 48 A

FDMC86340

Description

This N-Channel MOSFET is produced using onsemi's advanced POWETRENCH process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Features

- Shielded Gate MOSFET Technology
- Max $R_{DS(on)}$ = 6.5 mΩ at V_{GS} = 10 V, I_D = 14 A
- Max $R_{DS(on)}$ = 8.5 mΩ at V_{GS} = 8 V, I_D = 12 A
- High Performance Technology for Extremely Low $R_{DS(on)}$
- Termination is Lead-Free
- RoHS Compliant

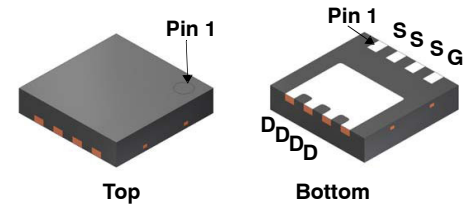
Applications

- DC-DC Conversion

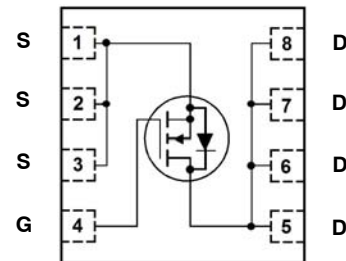
MAXIMUM RATINGS (T_A = 25°C unless otherwise specified)

Symbol	Parameter	Ratings	Unit
V_{DS}	Drain-to-Source Voltage	80	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Drain Current – Continuous		A
	T_C = 25°C	48	
	T_A = 25°C (Note 1a)	14	
	– Pulsed (Note 4)	200	
E_{AS}	Single Pulse Avalanche Energy (Note 3)	216	mJ
P_D	Power Dissipation		W
	T_C = 25°C T_A = 25°C (Note 1a)	54 2.3	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	–55 to +150	°C

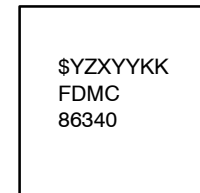
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



WDFN8
CASE 483AW



MARKING DIAGRAM



\$Y = onsemi Logo
Z = Assembly Plant Code
XY = Date Code (Year & Week)
KK = Lot Traceability Code
FDMC86340 = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping†
FDMC86340	WDFN8 (Pb-Free, Halide Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, [BRD8011/D](#).

THERMAL CHARACTERISTICS

Symbol	Parameter	Ratings	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case (Note 1)	2.3	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	53	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

BV_{DSS}	Drain-to-Source Breakdown Voltage	$I_D = 250\text{ }\mu\text{A}$, $V_{GS} = 0\text{ V}$	80	–	–	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to 25°C	–	46	–	$\text{mV}/^{\circ}\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 64\text{ V}$, $V_{GS} = 0\text{ V}$	–	–	1	μA
I_{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$	–	–	± 100	nA

ON CHARACTERISTICS

$V_{GS(th)}$	Gate-to-Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$	2.0	3.4	4.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate-to-Source Threshold Voltage Temperature Coefficient	$I_D = 250\text{ }\mu\text{A}$, referenced to 25°C	–	–10	–	$\text{mV}/^{\circ}\text{C}$
$R_{DS(on)}$	Static Drain-to-Source On Resistance	$V_{GS} = 10\text{ V}$, $I_D = 14\text{ A}$	–	5.0	6.5	$\text{m}\Omega$
		$V_{GS} = 8\text{ V}$, $I_D = 12\text{ A}$	–	6.0	8.5	
		$V_{GS} = 10\text{ V}$, $I_D = 14\text{ A}$, $T_J = 125^{\circ}\text{C}$	–	8.5	11	
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{ V}$, $I_D = 14\text{ A}$	–	36	–	S

DYNAMIC CHARACTERISTICS

C_{iss}	Input Capacitance	$V_{DS} = 40\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	–	2775	3885	pF
C_{oss}	Output Capacitance		–	468	655	pF
C_{rss}	Reverse Transfer Capacitance		–	15	25	pF
R_g	Gate Resistance		0.1	0.7	2.1	Ω

SWITCHING CHARACTERISTICS

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 40\text{ V}$, $I_D = 14\text{ A}$, $V_{GS} = 10\text{ V}$, $R_{GEN} = 6\text{ }\Omega$	–	20	32	ns
t_r	Rise Time		–	7.9	16	
$t_{d(off)}$	Turn-Off Delay Time		–	23	37	
t_f	Fall Time		–	5.1	10	
$Q_{g(tot)}$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to 10 V , $V_{DD} = 40\text{ V}$, $I_D = 14\text{ A}$	–	38	53	nC
$Q_{g(tot)}$	Total Gate Charge	$V_{GS} = 0\text{ V}$ to 8 V , $V_{DD} = 40\text{ V}$, $I_D = 14\text{ A}$	–	31	44	
Q_{gs}	Gate-to-Source Charge	$V_{DD} = 40\text{ V}$, $I_D = 14\text{ A}$	–	14	–	
Q_{gd}	Gate-to-Drain "Miller" Charge	$V_{DD} = 40\text{ V}$, $I_D = 14\text{ A}$	–	8.0	–	
Q_{oss}	Output Charge	$V_{DD} = 40\text{ V}$, $I_D = 0\text{ V}$	–	42	–	

FDMC86340

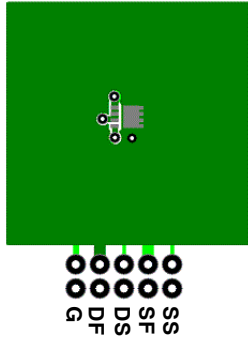
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
V _{SD}	Source-to-Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 14 A (Note 2)	–	0.80	1.3	V
		V _{GS} = 0 V, I _S = 1.9 A (Note 2)	–	0.7	1.2	V
t _{rr}	Reverse Recovery Time	I _F = 14 A, di/dt = 100 A/μs	–	41	66	ns
Q _{rr}	Reverse Recovery Charge		–	25	40	nC

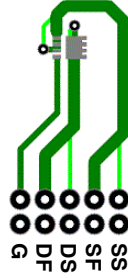
Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

NOTES:

1. R_{θJA} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 × 1.5 in. board of FR-4 material. R_{θJC} is guaranteed by design while R_{θCA} is determined by the user's board design.



a) 53°C/W when mounted on a 1 in² pad of 2 oz copper



b) 125°C/W when mounted on a minimum pad of 2 oz copper

2. Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.
3. E_{AS} of 216 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 12 A, V_{DD} = 80 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 37 A.
4. Pulsed Id limited by junction temperature, t_d ≤ 100 μs, please refer to SOA curve for more details.

TYPICAL CHARACTERISTICS

($T_J = 25^\circ\text{C}$ unless otherwise noted)

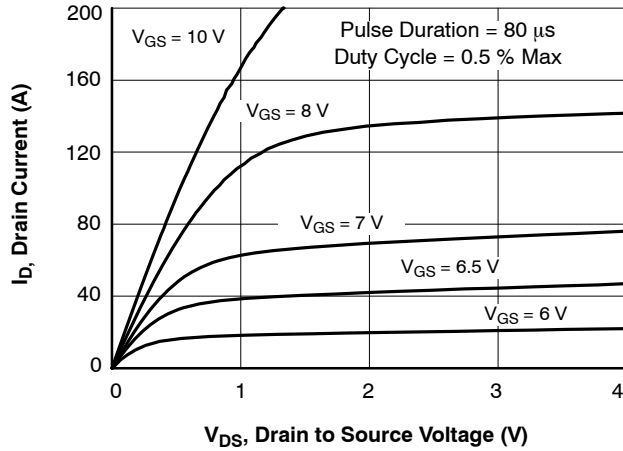


Figure 1. On-Region Characteristics

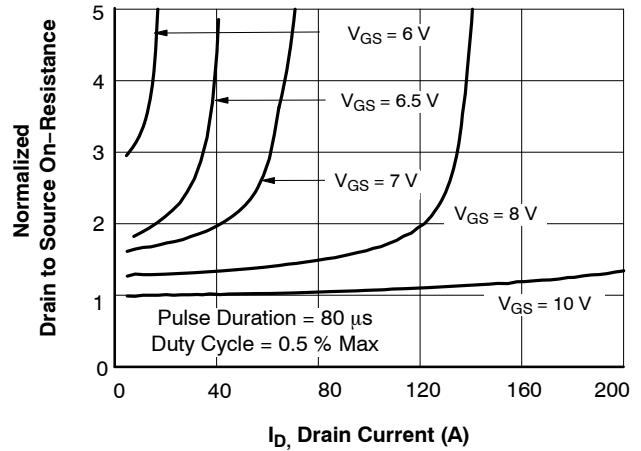


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

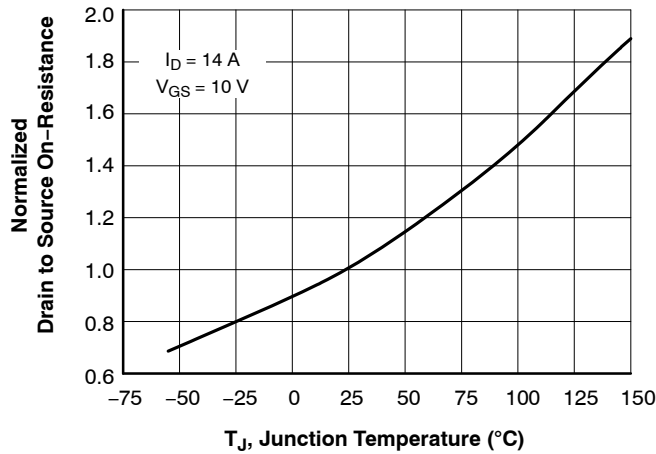


Figure 3. Normalized On-Resistance vs. Junction Temperature

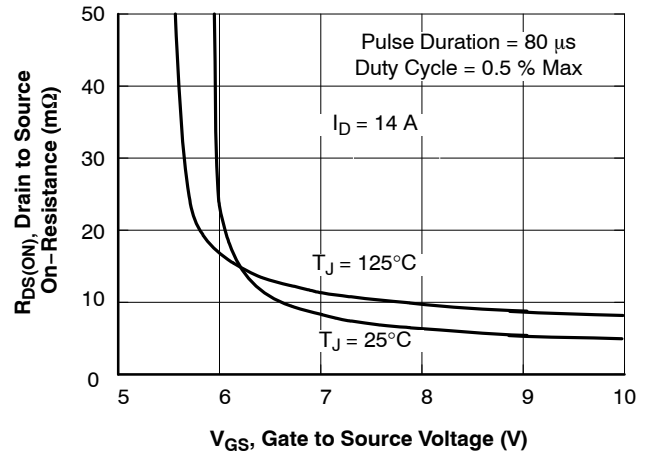


Figure 4. On-Resistance vs. Gate to Source Voltage

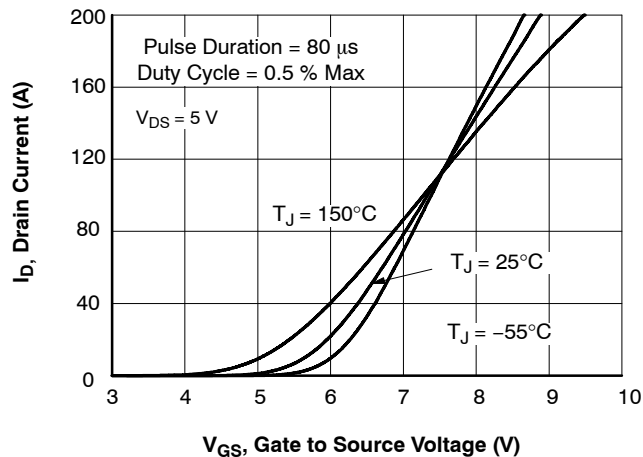


Figure 5. Transfer Characteristics

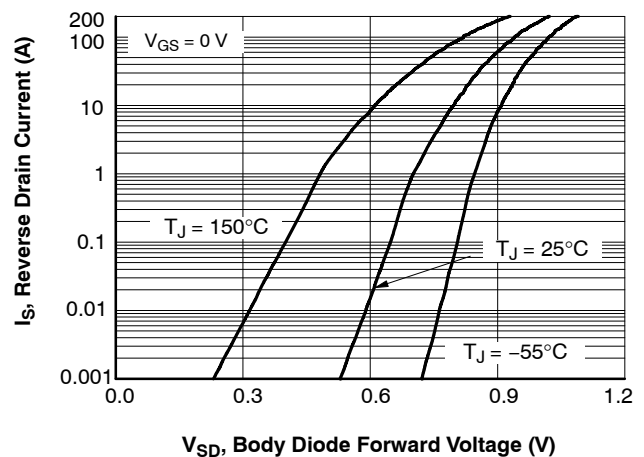


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

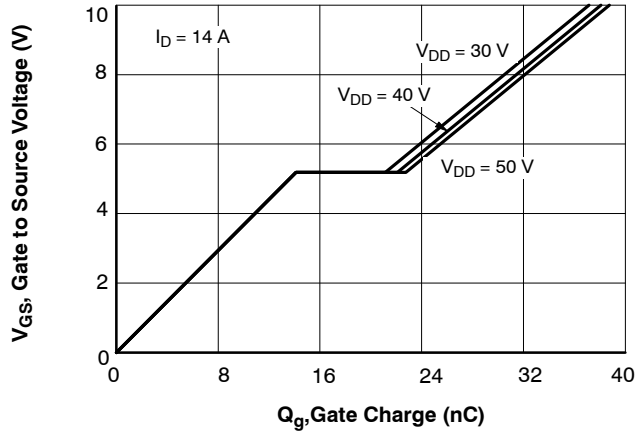


Figure 7. Gate Charge Characteristics

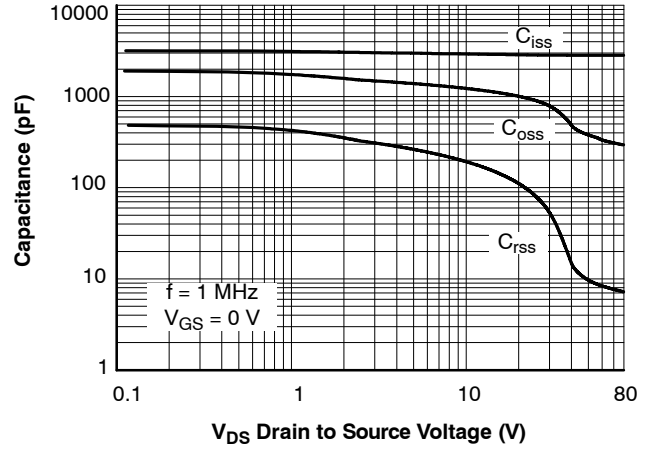


Figure 8. Capacitance vs Drain to Source Voltage

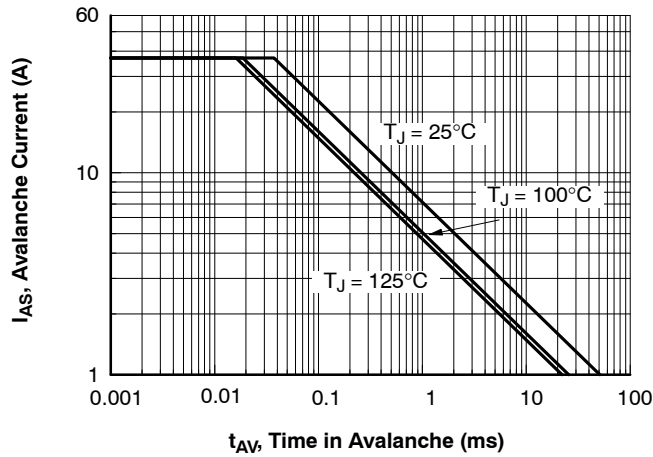


Figure 9. Unclamped Inductive Switching Capability

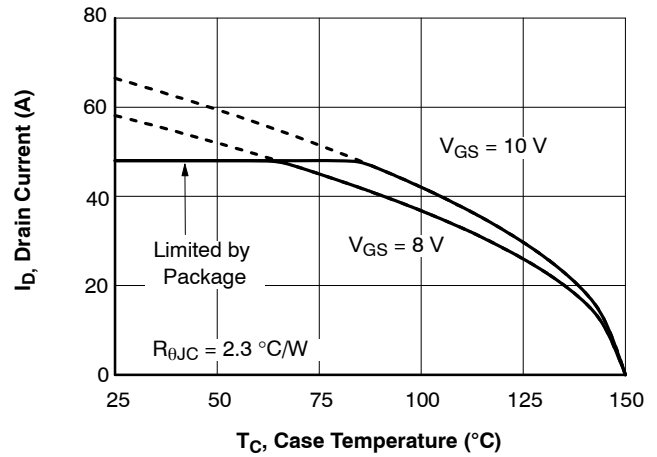


Figure 10. Maximum Continuous Drain Current vs. Case Temperature

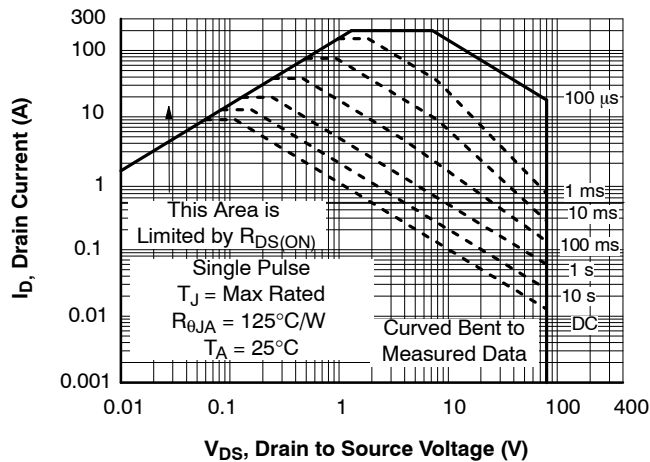


Figure 11. Forward Bias Safe Operating Area

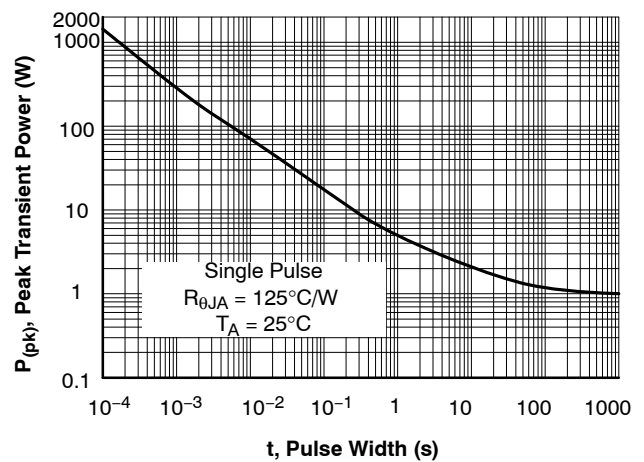


Figure 12. Single Pulse Maximum Power Dissipation

TYPICAL CHARACTERISTICS (continued)

($T_J = 25^\circ\text{C}$ unless otherwise noted)

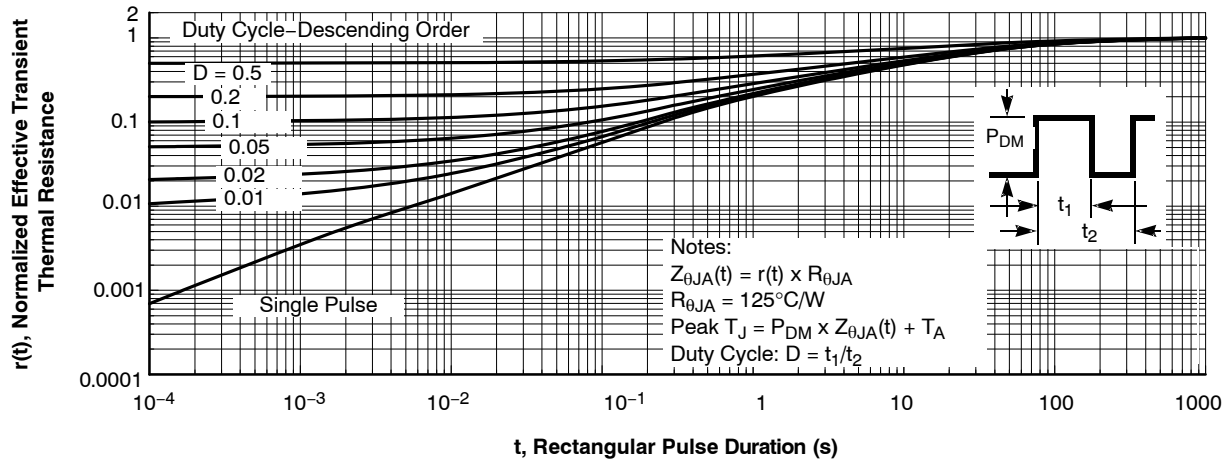
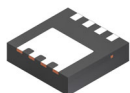


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

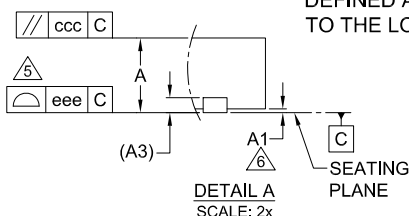
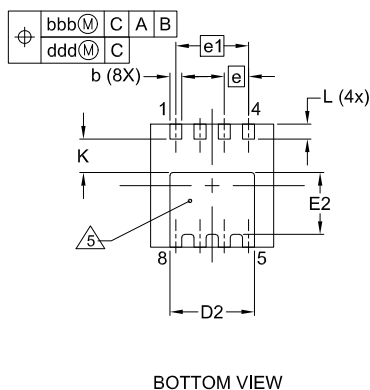
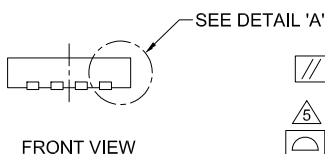
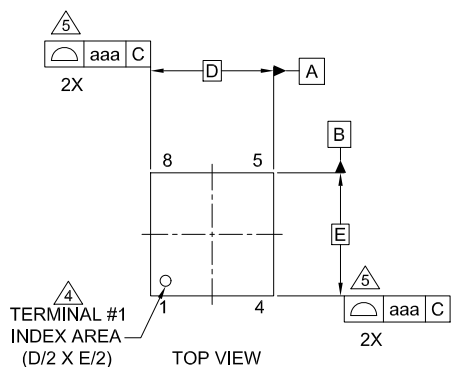


WDFN8 3.30x3.30x0.75, 0.65P

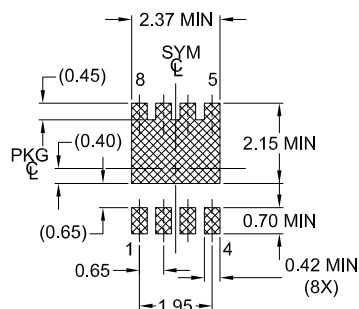
CASE 483AW

ISSUE B

DATE 22 MAR 2024



LAND PATTERN
RECOMMENDATION



NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
4. THE TERMINAL #1 IDENTIFIER AND TERMINAL NUMBERING CONVENTION SHALL CONFORM TO JEP95 SEC. 3 SPP-12. DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE TERMINAL #1 IDENTIFIER MAY BE EITHER A MOLD, EMBEDDED METAL OR MARKED FEATURE.
5. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
6. SEATING PLANE IS DEFINED BY THE TERMINALS. 'A1' IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	--	--	0.05
A3	0.20 REF		
b	0.27	0.32	0.37
D	3.30 BSC		
D2	2.17	2.27	2.37
E	3.30 BSC		
E2	1.56	1.66	1.76
e	0.65 BSC		
e1	1.95 BSC		
K	0.90	--	--
L	0.30	0.40	0.50
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.05		

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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